

UT6JE5

-100V Pch+Pch Power MOSFET

$V_{ m DSS}$	-100V
R _{DS(on)} (Max.)	840mΩ
I _D	±1.0A
P _D	2.0W

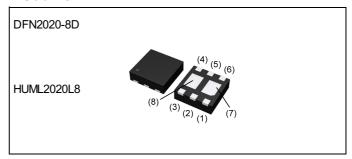
Features

- 1) Low on resistance
- 2) Small surface mount package
- 3) Pb-free plating; RoHS compliant
- 4) Halogen Free

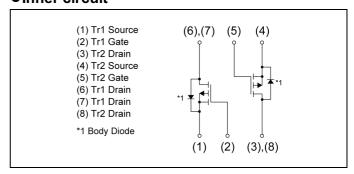
Application

Switching

Outline



●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Type	Tape width (mm)	8
	Quantity (pcs)	3000
	Taping code	TCR
	Marking	JE5

ullet Absolute maximum ratings (T_a = 25°C ,unless otherwise specified) <Tr1 and Tr2>

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	-100	V
Continuous drain current	I _D	±1.0	Α
Pulsed drain current	I _{DP} *1	±4.0	А
Gate - Source voltage	V_{GSS}	±20	V
Power dissipation (total)	P _D *2	2.0	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Lloit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R _{thJA} *2	1	-	62.5	°C/W

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

Davamatav	Cymah ol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Min. Typ. Max.		Unit
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = -1mA$	-100	-	-	V
Breakdown voltage	ΔV _{(BR)DSS}	I _D = -1mA		-68		mV/°C
temperature coefficient	ΔT _j	referenced to 25°C	-	-00	-	IIIV/ C
Zero gate voltage drain current	I _{DSS}	V _{DS} = -100V, V _{GS} = 0V		-	-1	μA
Gate - Source leakage current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V		-	±100	nA
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -1mA$		-	-2.5	V
Gate threshold voltage	$\Delta V_{GS(th)}$	I _D = -1mA		3.7		V/°C
temperature coefficient	ΔT_{j}	referenced to 25°C	-	3.1	-	V/ C
Static drain - source	D *3	$V_{GS} = -10V, I_D = -1A$	-	650	840	mΩ
on - state resistance	R _{DS(on)} *3	$V_{GS} = -4.5V, I_D = -1A$	-	690	900	11122
Gate resistance	R_{G}	f=1MHz, open drain	-	15	-	Ω
Forward Transfer Admittance	Y _{fs} *3	$V_{DS} = -5V, I_{D} = -1A$	1.3	-	-	S

^{*1} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*2} Mounted on a Cu board (40×40×0.8mm)

^{*3} Pulsed

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

Darameter	Symbol	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	V _{GS} = 0V	-	90	-	
Output capacitance	C _{oss}	V _{DS} = -50V	-	12	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	11	-	
Turn - on delay time	t _{d(on)} *3	$V_{DD} \simeq -50V, V_{GS} = -10V$	-	6.3	-	
Rise time	t _r *3	I _D = -0.5A	-	5.4	-	
Turn - off delay time	t _{d(off)} *3	R _L = 100Ω	-	31.0	-	ns
Fall time	t _f *3	$R_G = 10\Omega$	-	25.0	-	

● Gate charge characteristics (T_a = 25°C) < Tr1 and Tr2>

Darameter	Cymahal	Conditions		Values			l limit	
Parameter	Symbol			Min.	Тур.	Max.	Unit	
Total mate about	O *3		V _{GS} = -10V	-	6.7	-		
Total gate charge	Q_g^{*3}	V_{D}	V _{DD} ≃ -50V		-	3.7	-	0
Gate - Source charge	Q _{gs} *3	I _D = -1A	V _{GS} = -4.5V	-	1.2	-	nC	
Gate - Drain charge	Q _{gd} *3			-	1.5	-		

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

<Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit	
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Continuous forward current	I _S	T _a = 25°C	-	-	-1.67	^	
Pulse forward current	I _{SP} *1	1 _a – 25 C	-	-	-4.0	A	
Forward voltage	V _{SD} *3	V _{GS} = 0V, I _S = -1.67A	-	-	-1.2	V	
Reverse recovery time	t _{rr} *3	I _S = -1A, V _{GS} = 0V	-	22	-	ns	
Reverse recovery charge	Q _{rr} *3	di/dt = 100A/μs	-	53	-	nC	

Fig.1 Power Dissipation Derating Curve

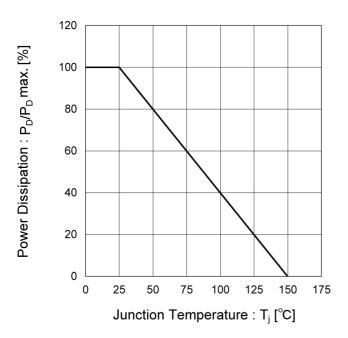
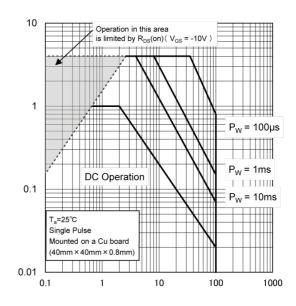


Fig.2 Maximum Safe Operating Area



Drain Current : -l_D [A]

Drain - Source Voltage : -V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

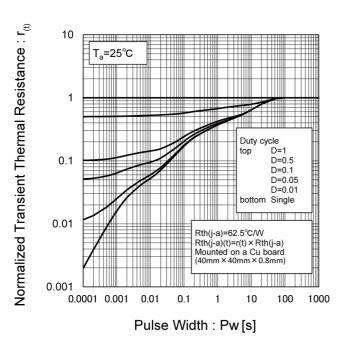


Fig.4 Single Pulse Maximum Power Dissipation

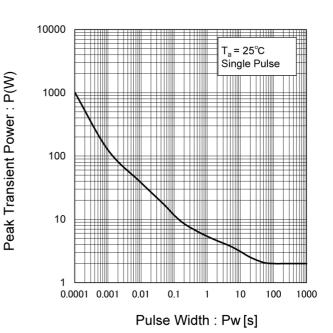


Fig.5 Typical Output Characteristics(I)

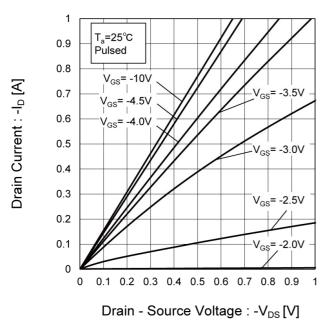


Fig.6 Typical Output Characteristics(II)

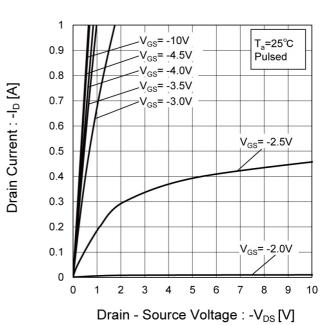
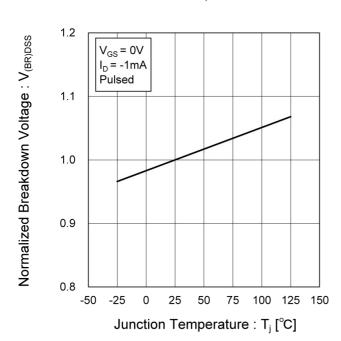


Fig.7 Normalized Breakdown Voltage vs. **Junction Temperature**



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Fig.8 Typical Transfer Characteristics

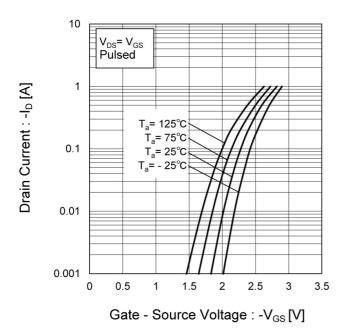


Fig.9 Gate Threshold Voltage vs.
Junction Temperature



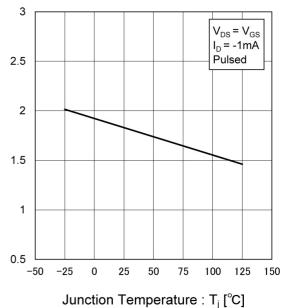


Fig.10 Forward Transfer Admittance vs.
Drain Current

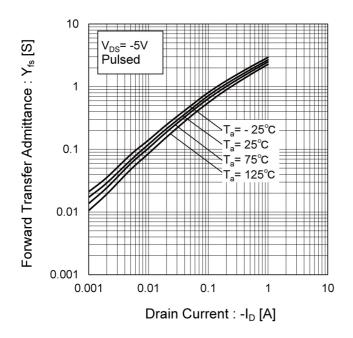


Fig.11 Drain Current Derating Curve

120 100 **Drain Current Dissipation** 80 : I_D/I_Dmax. [%] 60 40 20 0 -25 0 25 50 75 100 125 150 Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

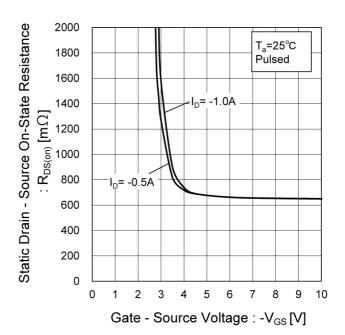
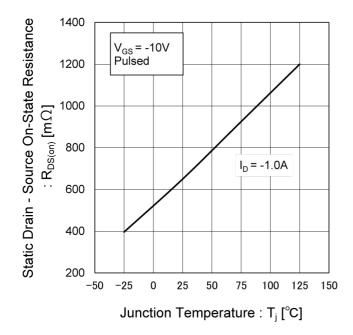


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



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Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

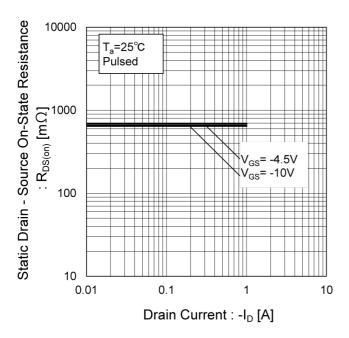


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

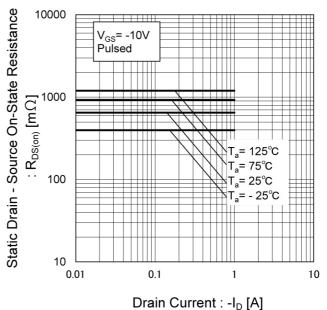
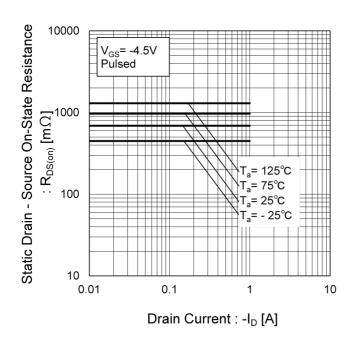


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)



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Fig.17 Typical Capacitances vs.

Drain - Source Voltage

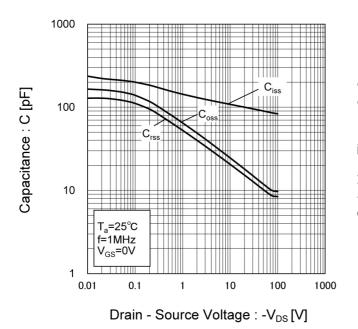


Fig.18 Switching Characteristics

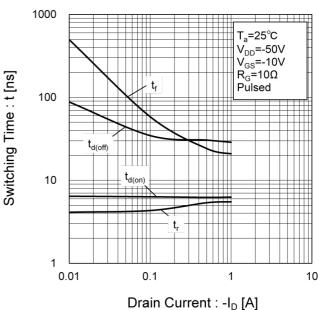
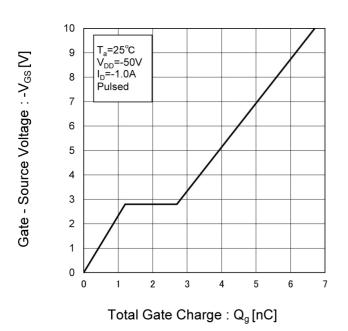


Fig.19 Typical Gate Charge



Source Current : -l_s [A]

10 | V_{GS}=0V | Pulsed | 1 | T_a= 125°C | T_a= 75°C | T_a= 25°C | T_a= - 25°C

Fig.20 Source Current vs.

Source Drain Voltage

• Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

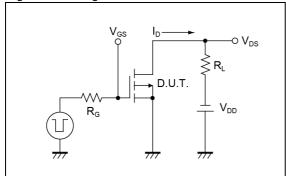


Fig.2-1 Gate Charge Measurement Circuit

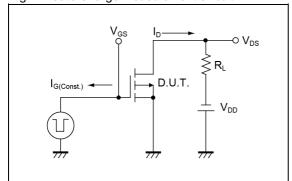


Fig.1-2 Switching Waveforms

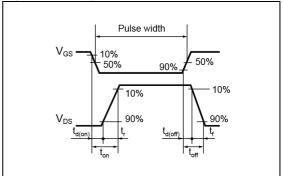
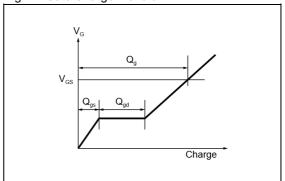


Fig.2-2 Gate Charge Waveform

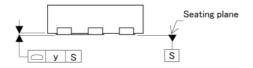


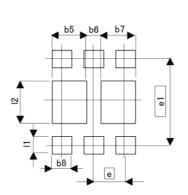
Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

Dimensions

DFN2020-8D





Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIME	MILIMETERS		HES
DIIVI	MIN	MAX	MIN	MAX
Α	0.55	0.65	0.022	0.026
A1	0.00	0.05	0.000	0.002
b	0.25	0.35	0.010	0.014
b1	0.	25	0.0)10
b2	0.60	0.70	0.024	0.028
b3	0	.3	0.012	
b4	0.60	0.70	0.024	0.028
D	1.90	2.10	0.075	0.083
E	1.90	2.10	0.075	0.083
е	0.	0.65)26
Lp	0.225	0.325	0.009	0.013
Lp1	0.80	1.00	0.031	0.039
х	-	0.10		0.004
у	-	0.10	0. - 0	0.004

DIM	MILIME	ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
b5	ī	0.70	(0-)	0.028
b6	0.20	0.30	0.008	0.012
b7	ī	0.70	-	0.028
b8	1	0.45	-	0.018
e1	1.7	725	0.068	
l1	ı	0.425	15	0.017
12	-	1.00	-	0.039

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	ОГУООШ	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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